

LPKF MiniContac S

Exceptional PCB electroplating in a compact table-top unit

- Compact, high-quality in-house PCB electroplating
- Plates an unlimited number of holes in just 90 minutes
- Plates a minimum hole diameter of 0.015" with a 1:5 aspect ratio
- Integrates easily with existing mechanical PCB prototyping equipment

LPKF MiniContac S

The LPKF MiniContac S PCB electroplating system is a low-cost and compact through-hole plating unit that employs the formaldehyde-free Blackhole® technology. It fits on a table-top or a workbench, making it easy to add to a small engineering area. Its panel size complements the working area of the LPKF ProtoMat® C-Series circuit board plotters, so the MiniContac-S conveniently integrates into existing PCB prototype systems. It provides an inexpensive and complete in-house circuit board plating solution that eliminates the need for outside board production services.

The MiniContac S can plate an unlimited number of holes, and it provides exceptional plating quality for double-sided and multilayer prototype boards. It can plate aspect ratios up to 1:5, resulting in plated through-holes as small as 0.4 mm (0.015 in) in boards 59 mils thick. The system is compatible with most common circuit board materials, including FR4 (G10), FR5, and microwave substrates such as RO3000®, RO4000® and TMM®. Its efficiency is reflected by the reduced number of treatment baths required to complete the plating process.

The environmentally friendly safety design of the MiniContac S ensures complete system integrity because it is a closed system and the consumables stay in the tank during operation. All consumables are reliable and maintenance-free, and they are guaranteed for 12 months. Air and drain water analysis is provided, and LPKF also supplies a complete and easy disposal solution for the consumables.



LPKF MiniContac S PCB electroplating system



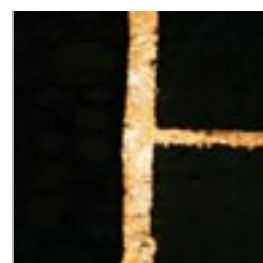
Cross section of through-hole in a 4-layer circuit board



Plated through-hole



Cross section of top copper layer connecting to plated through-hole



Cross section of inner copper layer connecting to plated through-hole

LPKF MiniContac S - Specifications

Dimensions	23.6" x 21.6" x 21.6" (600 mm x 550 mm x 550 mm)
Minimum hole diameter	0.015" (0.4 mm) with 59 mil board material
Number of plated holes	Unlimited
Maximum number of layers	4
Process duration	90 minutes
Max. number of layers	4
Maximum panel size	9" x 13" (230 mm x 330 mm)
Base material types	FR4, FR5, RO3000, RO4000, TMM*
Maximum resistance	Less than 0.01 Ohm
Ambient temperature	64° - 77° F (18° - 25° C)
Power supply	240 V/50-60 Hz, 120 V/50-60 Hz
Via hole activation	Blackhole® (carbon dispersion)

* other materials on request

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